DATA SHEET



Solid State Relay OCMOS FET

PS7241-2A

8-PIN SOP, 400V BREAK DOWN VOLTAGE 2-ch Optical Coupled MOS FET

DESCRIPTION

The PS7241-2A is a solid state relay containing GaAs LEDs on the light emitting side (input side) and normally open (N.O.) contact MOS FETs on the output side.

It is suitable for analog signal control because of their low offset and high linearity.

FEATURES

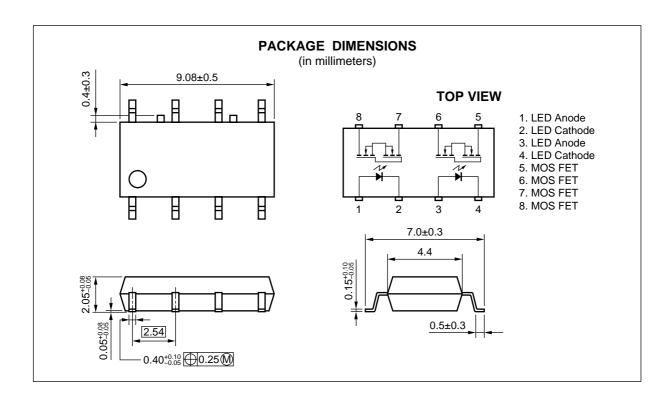
- 2 channel type (1 a + 1 a output)
- Low LED operating current (IF = 2 mA)
- · Designed for AC/DC switching line changer
- Small and thin package (8-pin SOP, Height = 2.1 mm)
- · Low offset voltage
- Ordering number of taping product: PS7241-2A-F3, F4
- UL approved: File No. E72422 (S)
- BSI approved: No. 8241/8242
- CSA approved: No. CA 101391

APPLICATIONS

- · Exchange equipment
- · Measurement equipment
- FA/OA equipment

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.





ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number*1
PS7241-2A	8-pin SOP	Magazine case 45 pcs	PS7241-2A
PS7241-2A -F3		Embossed Tape 1 500 pcs/reel	
PS7241-2A -F4			

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	lf	50	mA	
	Reverse Voltage	VR	5	V	
	Power Dissipation	PD	50	mW/ch	
	Peak Forward Current*1	IFP	1	Α	
MOS FET	MOS FET Break Down Voltage		400	V	
	Continuous Load Current	lι	120	mA	
	Pulse Load Current ^{*2} (AC/DC Connection)	ILP	200	mA	
	Power Dissipation	Po	180	mW/ch	
Isolation Voltage*3		BV	1 500	Vr.m.s.	
Total Power Dissipation		Рт	460	mW	
Operating Ambient Temperature		TA	-40 to +85	°C	
Storage Temperature		T _{stg}	-40 to +100	°C	

^{*1} PW = 100 μ s, Duty Cycle = 1 %

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^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

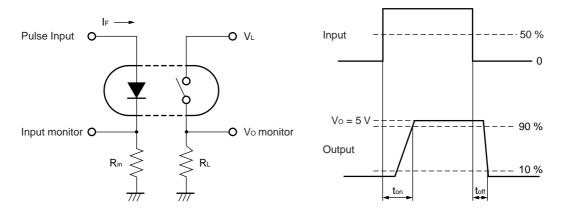
RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

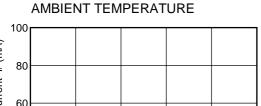
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lr	V _R = 5 V			5	μΑ
MOS FET	Off-state Leakage Current	Loff	V _D = 400 V		0.03	1.0	μΑ
	Output Capacitance	Cout	V _D = 0 V, f = 1.0 MHz		65		pF/ch
Coupled	LED On-state Current	IFon	IL = 120 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 10 mA		21	30	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 120 \text{ mA}, t \le 10 \text{ ms}$		16	25	
	Turn-on Time [™]	ton	IF = 10 mA, Vo = 5 V, RL = 500 Ω ,		0.2	1.0	ms
	Turn-off Time [™]	toff	PW ≥ 10 ms		0.02	0.2	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10°			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.4		pF/ch

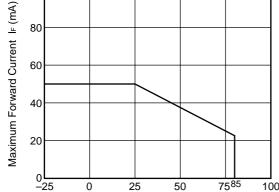
*1 Test Circuit for Switching Time



TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)

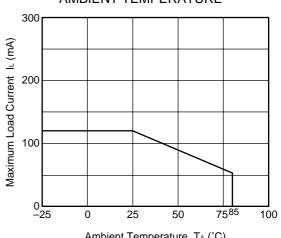


MAXIMUM FORWARD CURRENT vs.



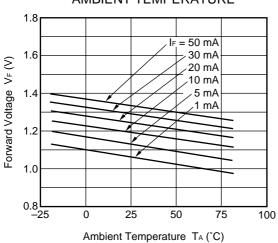
Ambient Temperature TA (°C)

MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE

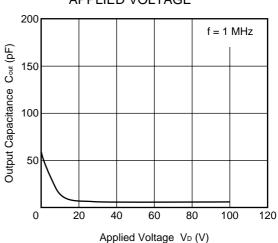


Ambient Temperature TA (°C)

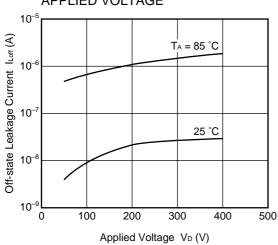
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



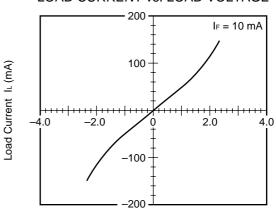
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



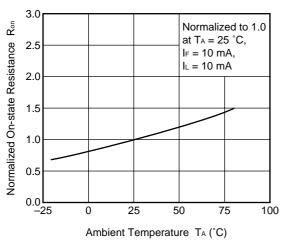
LOAD CURRENT vs. LOAD VOLTAGE



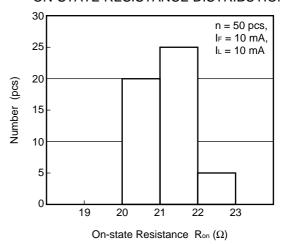
Load Voltage V_L (V)

NEC

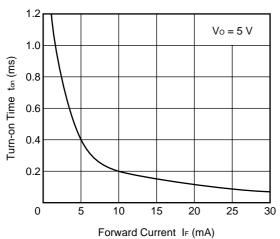
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



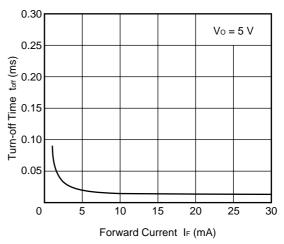
ON-STATE RESISTANCE DISTRIBUTION



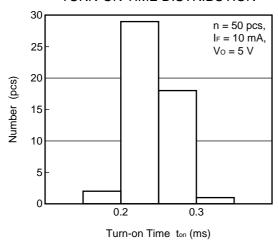
TURN-ON TIME vs. FORWARD CURRENT



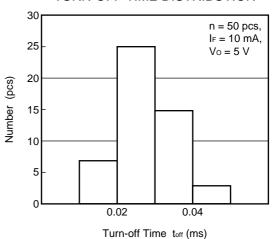
TURN-OFF TIME vs. FORWARD CURRENT



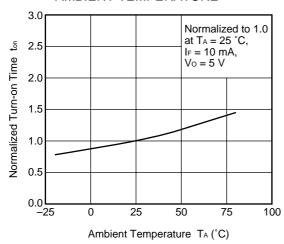
TURN-ON TIME DISTRIBUTION



TURN-OFF TIME DISTRIBUTION

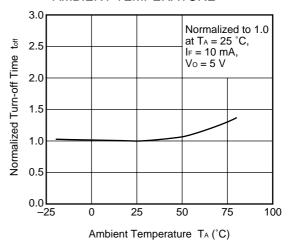


NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

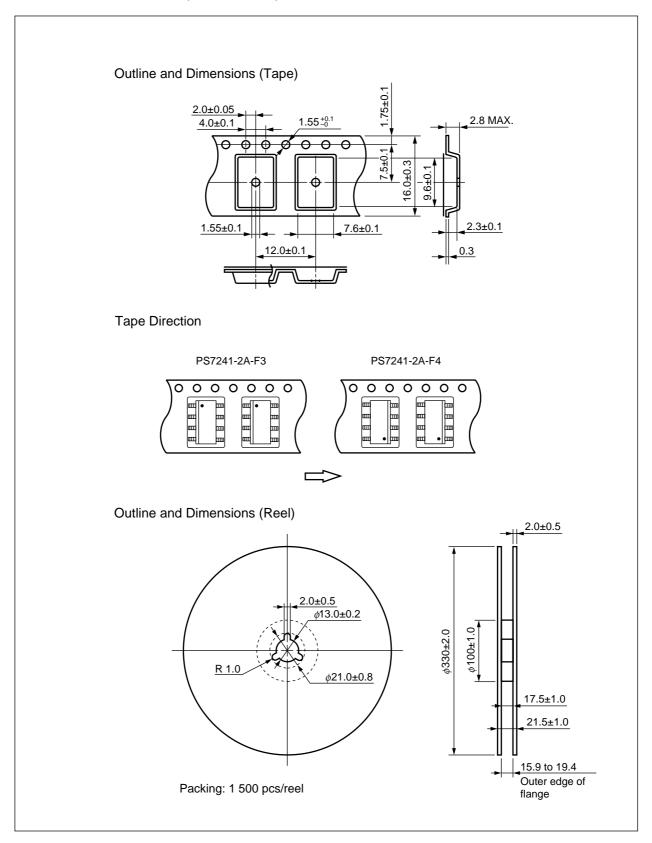


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



★ TAPING SPECIFICATIONS (in millimeters)





* RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

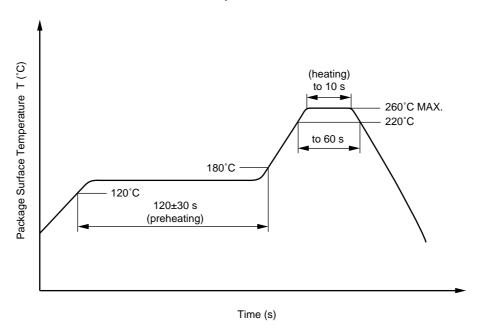
Time of peak reflow temperature
 Time of temperature higher than 220°C
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Cautions

(2) Wave soldering

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110



SAFETY INFORMATION ON THIS PRODUCT

Cai	Ition

GaAs Products

The product contains gallium arsenide, GaAs.

GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not destroy or burn the product.
- Do not cut or cleave off any part of the product.
- Do not crush or chemically dissolve the product.
- Do not put the product in the mouth.

Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

▶For further information, please contact

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